QUECTEL

Statement

We **Quectel Wireless Solutions Co., Ltd** declare the following models.

Product Name: Wi-Fi & Bluetooth Module
Model Number: FCM363X
Hardware Version: R1.0, R1.1
Software Version: FCM363XAAR02A02M08

Model Number: FCM363X-L
Hardware Version: R1.0
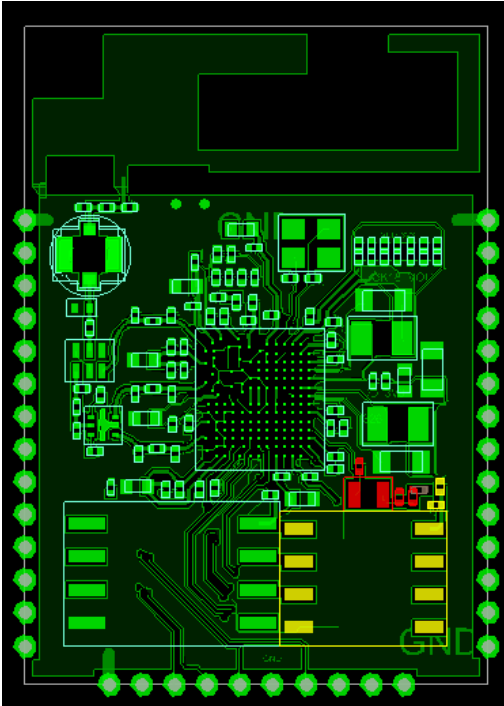**Software Version:** FCM363XLAAR02A02M08

FCM363X (R1.0, R1.1) both use NXP RW610UK/A2IZ chipset, share the same chipset baseline, same PCB design, and they support the same frequency bands. The main difference is that FCM363X (R1.0) does not have low power 32k crystal and PSRAM materials, while FCM363X (R1.1) has 32k crystal and RAM chip. 32kHz crystal is for BB timer hibernation to reduce power consumption, it is not the crystal for BT/Wi-Fi RF operation.

FCM363X (R1.0) and FCM363X-L both use NXP RW610UK/A2IZ chipset, share the same chipset baseline, same software, the main difference is FCM363X has 38 LCC pins and 35 LGA pins, while FCM363X-L has 38 LCC pins and 9 LGA pins, LGA pins from 39 to 64 are deleted. 38 LCC pins and 9 LGA pins that at the same position are totally same.
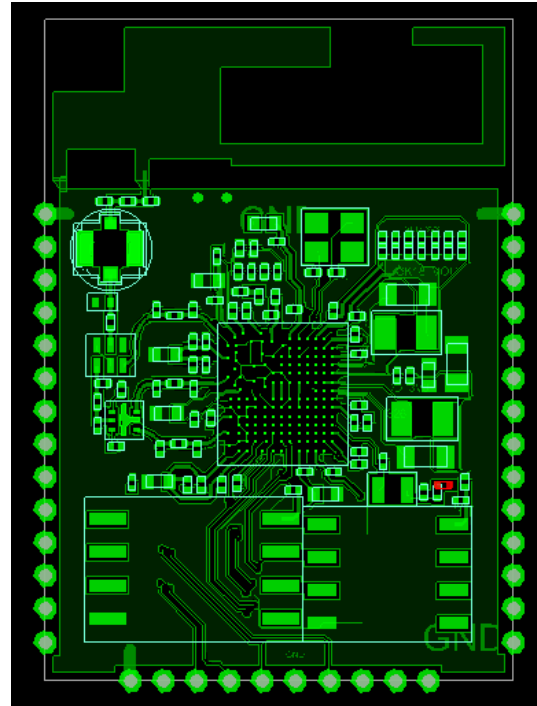
Module	Hardware Version	PMN	Chipset	Differences
FCM363X	R1.1	QUECTEL FCM363XACMD	RW610UK/A2IZ	1. X0202. 32k crystal clock model TFX-04-32.768KJ91233. Manufacturer is RIVER. C0204 and C0205 are the load capacitors of X0202. 2. Delete R0203 and add R0204. Configure X0202 to provide 32K clock signal. 3. U0202. PSRAM model APS6404L-SQH-SN. Manufacturer is AP. C0206 C0207 are the power supply capacitors of U0202.
FCM363X	R1.0	QUECTEL FCM363X	RW610UK/A2IZ	1. Delete X0202 C0204 C0205. 2. Delete R0204 and add R0203. Configure external 32K clock signal. 3. Delete U0202 C0206 C0207.

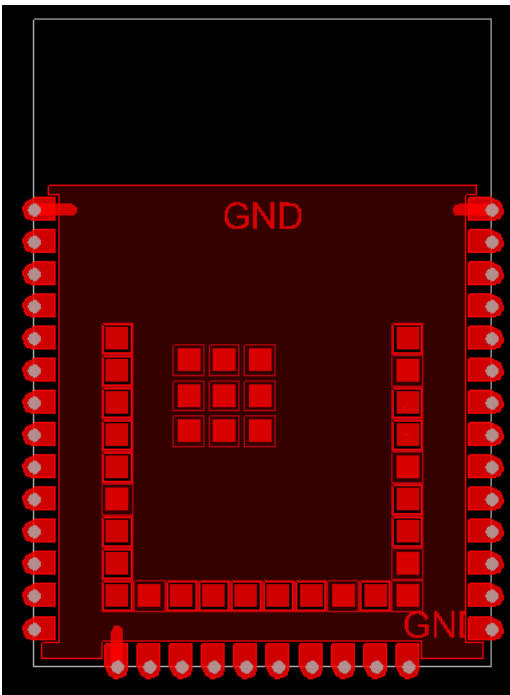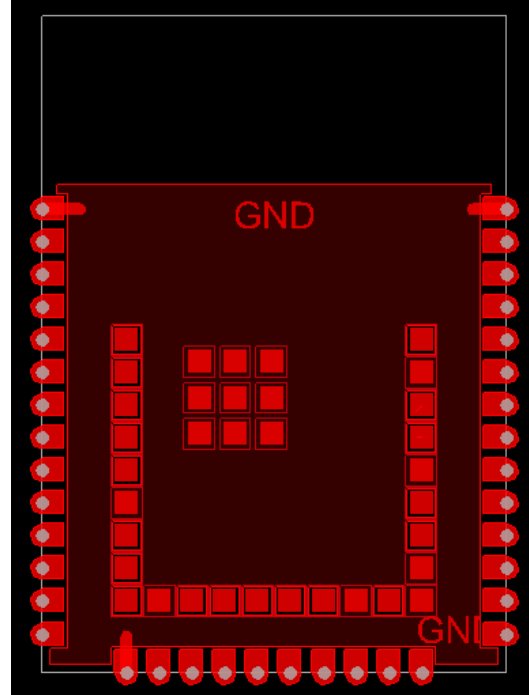| Module	Hardware Version	PMN	Chipset	Differences
FCM363X	R1.0	QUECTEL FCM363X	RW610UK/A2IZ	1. R0203 to LGA pin55(32k clk input) 2. 8MB flash is XM25QH64DHIQT, Manufacturer is XMC 3. PCB has 38 LCC pins and 35 LGA pins The module PIN25 is connected to the D4 pin of the RW610 chip. D4 is assigned to be used as GPIO function.
FCM363X-L	R1.0	QUECTEL FCM363X-L	RW610UK/A2IZ	1. Delete R0203(relevant LGA pin55 deleted) 2. 8MB flash is MX25L6433FM2I-08G, Manufacturer is MXIC 3. PCB has 38 LCC pins and 9 LGA pins(LGA 39~64 pins deleted) 4. The module PIN25 is connected to the U4 pin of the RW610 chip. U4 is assigned to be used as GPIO function.

- **SMT Differences**

FCM363X (R1.1) TOP
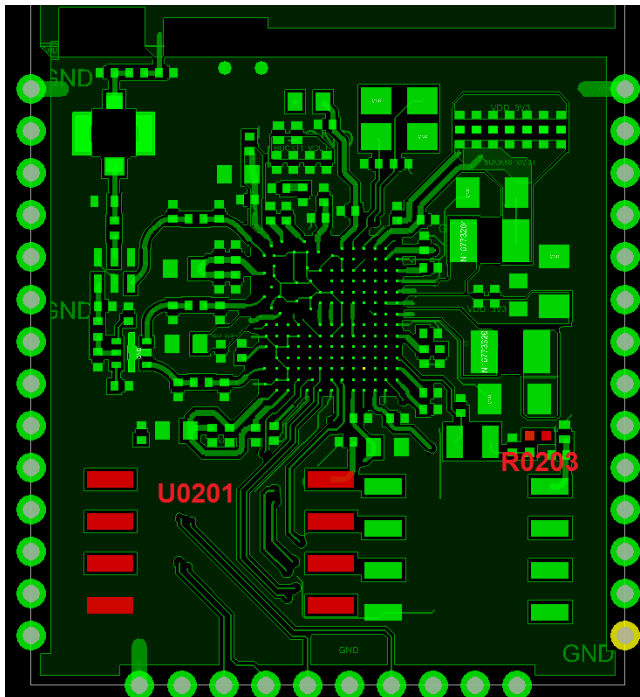

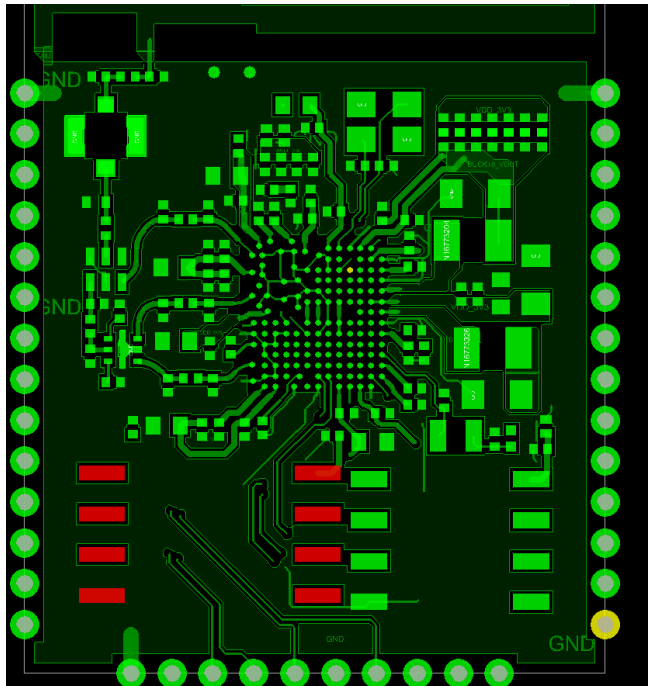FCM363X (R1.0) TOP

FCM363X (R1.1) BOT

FCM363X (R1.0) BOT

- **HW Difference Table**

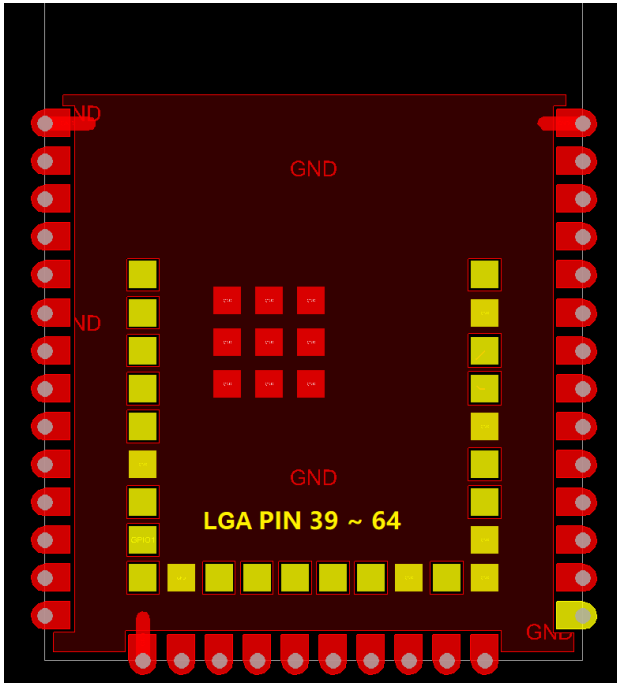| Designator	FCM363X (R1.1) (Part Description)	FCM363X (R1.0) (Part Description)
X0202	Has	Delete
C0204	Has	Delete
C0205	Has	Delete
R0203	Delete	Has
R0204	Has	Delete
U0202	Has	Delete
C0206	Has	Delete
C0207	Has	Delete

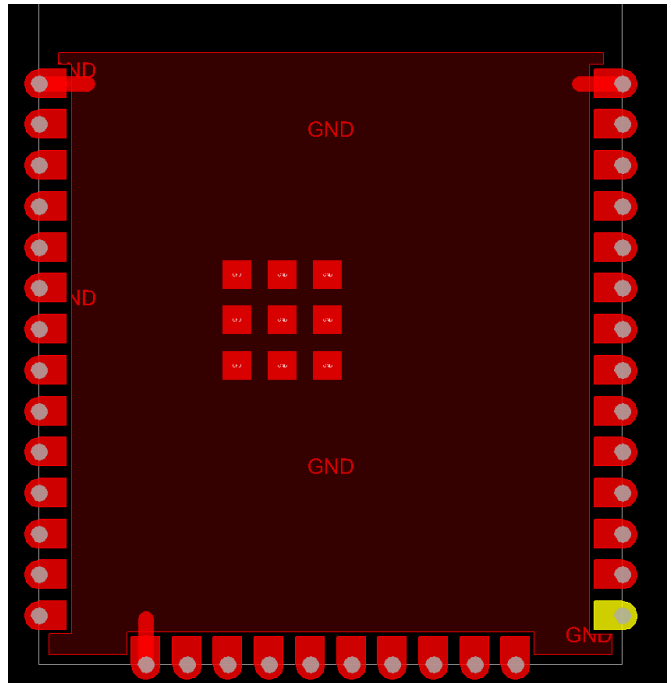- **PCB Layout changes**

FCM363X (R1.0) TOP   FCM363X-L TOP

FCM363X (R1.0) BOT

FCM363X-L BOT

- **HW Difference Table**

Designator	FCM363X (R1,0) (Part Description)	FCM363X-L (Part Description)
R0203	Has	Delete
U0201	8MB flash is XM25QH64DHIQT, Manufacturer is XMC	8MB flash is MX25L6433FM2I-08G, Manufacturer is MXIC
PCB	Has 38 LCC pins and 35 LGA pins	Has 38 LCC pins and 9 LGA pins(LGA 39~64 pins deleted)
PCB	The module PIN25 is connected to the D4 pin of the RW610 chip.	The module PIN25 is connected to the U4 pin of the RW610 chip.

Above changes won't impact the protocol and RF performance for same frequency. Your assistance on this matter is highly appreciated.

Person responsible for making this statement.

Name/Surname:

Position/Title: Certification Manager
Issue Date: June 23, 2025